

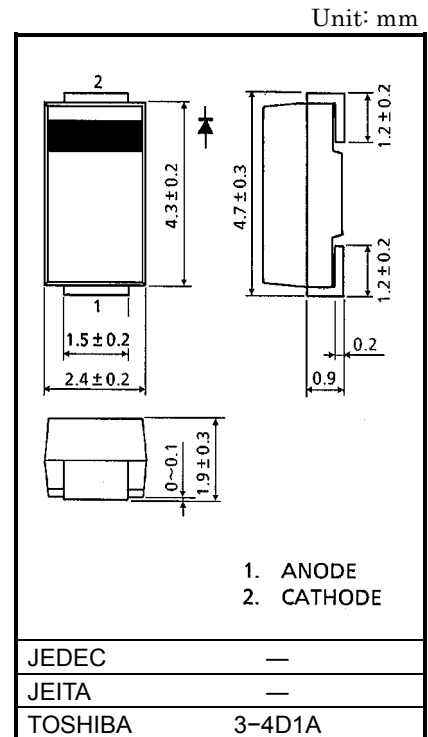
# U2GWJ44

## SWITCHING MODE POWER SUPPLY APPLICATION

- Low Forward Voltage :  $V_{FM} = 0.55V$  (Max)
- Average Forward Current :  $I_F (AV) = 2.0A$
- Repetitive Peak Reverse Voltage :  $V_{RRM} = 40V$
- Surface Mounting Plastic Mold Package

## MAXIMUM RATINGS ( $T_a = 25^\circ C$ )

CHARACTERISTIC	SYMBOL	RATING	UNIT
Repetitive Peak Reverse Voltage	$V_{RRM}$	40	V
Average Forward Current	$I_F (AV)$	2.0	A
Peak One Cycle Surge Forward Current (Non-Repetitive)	$I_{FSM}$	40 (50 Hz)	A
Junction Temperature	$T_j$	-40~125	$^\circ C$
Storage Temperature Range	$T_{stg}$	-40~125	$^\circ C$

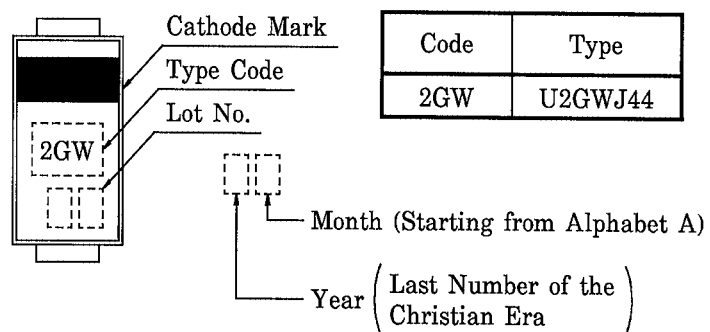
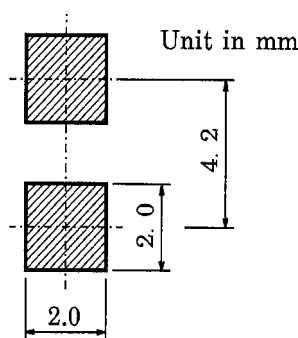


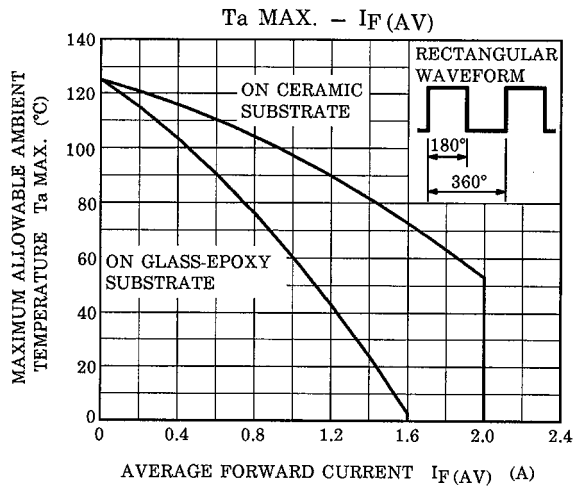
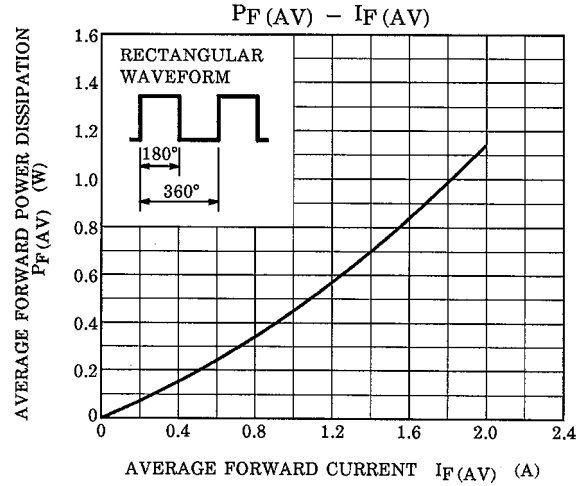
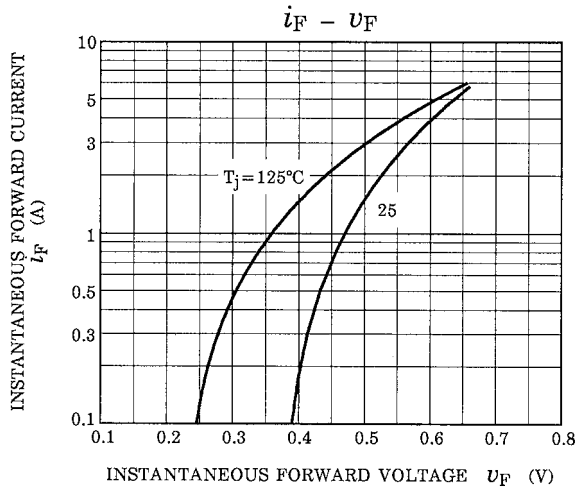
## ELECTRICAL CHARACTERISTICS ( $T_a = 25^\circ C$ )

Weight: 0.06g

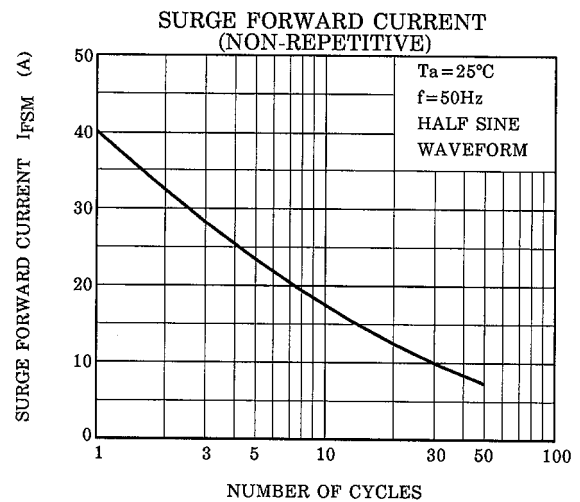
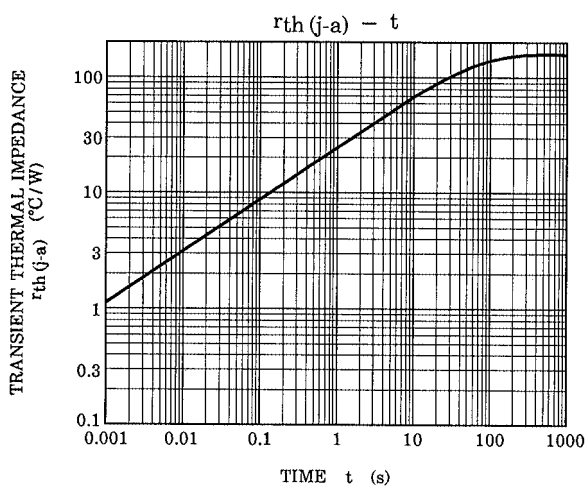
CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN	TYP.	MAX	UNIT
Peak Forward Voltage	$V_{FM}$	$I_{FM} = 2.0A$	—	—	0.55	V
Repetitive Peak Reverse Current	$I_{RRM}$	$V_{RRM} = 40V$	—	—	500	$\mu A$
Junction Capacitance	$C_j$	$V_R = 10V, f = 1.0MHz$	—	125	—	pF
Thermal Resistance (Junction to Ambient)	$r_{th (j-a)}$	On ceramic substrate	—	—	60	$^\circ C / W$
		On glass-epoxy substrate	—	—	145	

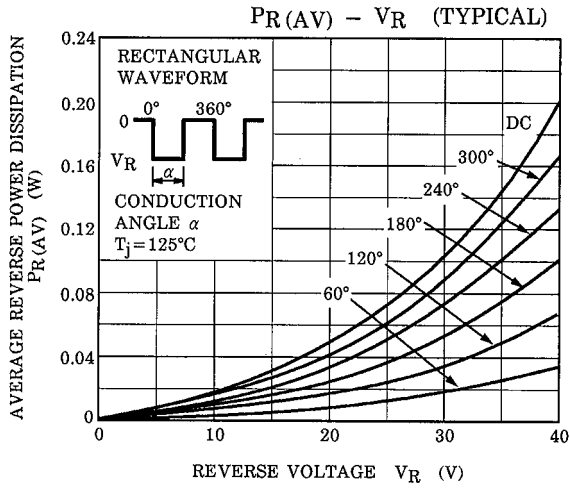
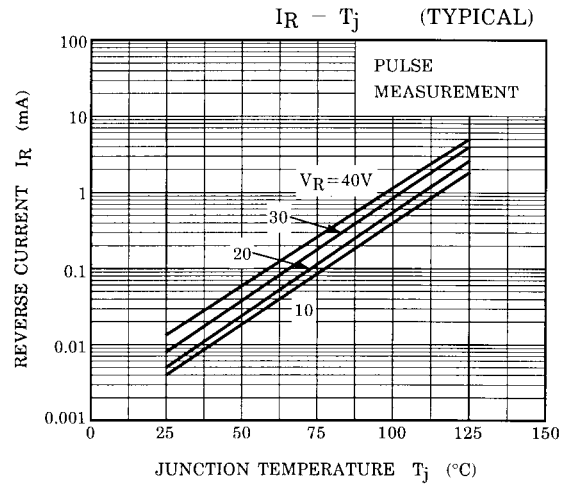
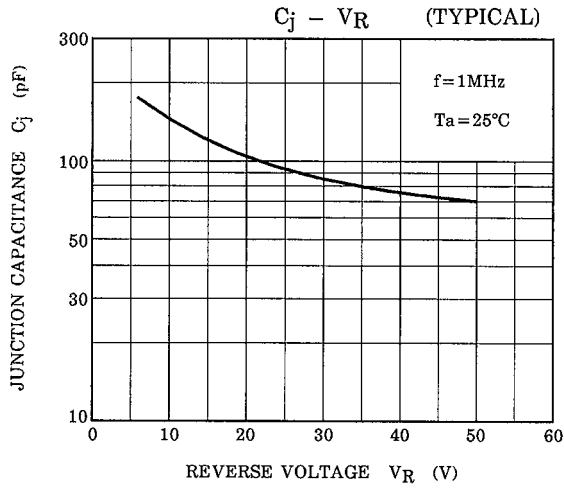
## STANDARD SOLDERING PAD MARKING





	ON CERAMIC SUBSTRATE	ON GLASS-EPOXY SUBSTRATE
Soldering land : a	2mm×2mm	6mm×6mm
Substrate size : b	50mm×50mm	50mm×50mm
Substrate thickness : c	0.64mm	1.6mm





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